TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN#20140227000
Green Mold Compound Conversion for LMP7704MT(X)/NOPB
Change Notification / Sample Request

Date: 2/28/2014
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20140227000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMP7704MT/NOPB	LMP7704MT NOPB
LMP7704MT/NOPB	LMP7704MT/NOPB

Technical details of this Product Change follow on the next page(s).

PCN Number:	20140227000	**PCN Date:**	02/28/2014
Title:	Green Mold Compound Conversion for LMP7704MT(X)/NOPB		
Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037
Dept:	Quality Services		
Proposed 1st Ship Date:	06/01/2014	**Estimated Sample Availability:**	03/01/2014

Change Type:

☐ Assembly Site	☐ Assembly Process	☒ Assembly Materials
☐ Design	☐ Electrical Specification	☐ Mechanical Specification
☐ Test Site	☐ Packing/Shipping/Labeling	☐ Test Process
☐ Wafer Bump Site	☐ Wafer Bump Material	☐ Wafer Bump Process
☐ Wafer Fab Site	☐ Wafer Fab Materials	☐ Wafer Fab Process
	☐ Part number change	

PCN Details

Description of Change:

The LMP7704MT(X)/NOPB devices will undergo a conversion to green mold compound. No other BOM changes are included in this notification:

	Current	New
Mold Compound	8064463	**4209002**

Reason for Change:

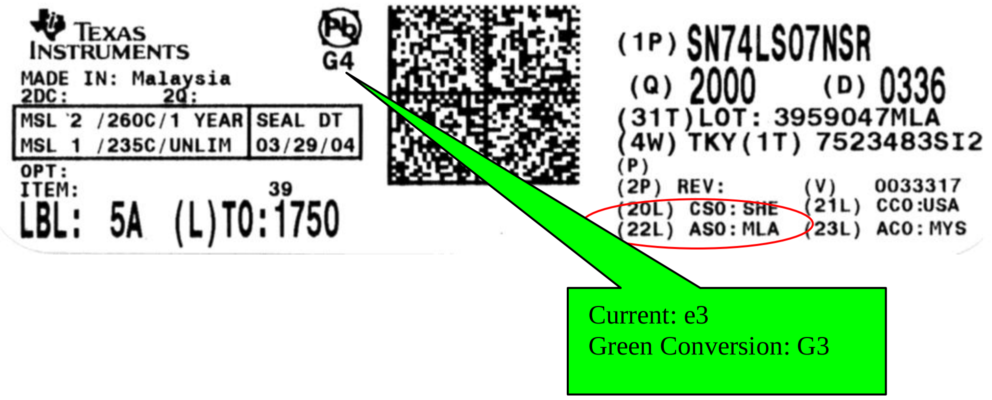
ROHS compliancy.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Sample product shipping label – Matte Sn Finish (not actual product label)



TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

G4

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Current: e3
Green Conversion: G3

Product Affected	
LMP7704MT/NOPB	LMP7704MTX/NOPB

Qualification Data: Approved November, 2009

Qual Vehicle: LMP2234AMTX/NOPB (MSL1-260C)

Package Construction Details

Assembly Site:	TIEM	**Mold Compound:**	4209002
# Pins-Designator, Family:	14-PW, TSSOP	**Mount Compound:**	8080598
Lead Finish:	Matte Sn	**Bond Wire:**	Au, 1.0 mil

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail	
		Lot#1	**Lot#2**
SOPL	125C (1000 Hrs)	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	45/0	45/0
**T/C -65C/150C	-65C/+150C (1000 Cyc)	77/0	70/0

** - Test requires Moisture Preconditioning (MSL1-260C)

Reference Qualification Data: Approved May, 2007

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LMB4008M1-6/NOPB (MSL 2A-260C)

Package Construction Details

Assembly Site:	TIEM	**Mold Compound:**	4209002
# Pins-Designator, Family:	DW-20, SOIC	**Mount Compound:**	8080598
Lead Finish:	Matte Sn	**Bond Wire:**	Au, 1.0 mil

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
SOPL	150C (1000 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**THBT	85C/85%RH (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (1000 Cyc)	77/0	77/0	77/0

Notes: **Tests require preconditioning sequence: MSL2A-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com